

Abstract

According to an example embodiment, the present invention is directed to a CMP apparatus having a polishing table, a wafer carrier adapted to carry a wafer on a pad, and a conditioning wheel. If the pad is being polished in a center-fast or center-slow manner, the conditioning wheel is used to condition the pad and to improve the center-fast or center-slow condition. Benefits of using this embodiment include improved wafer quality, improved pad life, a reduction in defective wafers, and faster production.